

### Description

Yantel's surface mount catalog bandpass filters utilize Yantel's low loss temperature stable materials which offer small size and minimal performance variation over temperature. The catalog BPF's are offered in a variety of frequency bands, which offers a drop in solution with highly repeatable performance.

### Features

- Small Size
- Fully Shielded Component
- Solder Surface Mount Package
- Moisture Sensitivity Level: MSL1
- Frequency Stable over Temperature
- Operating & Storage Temp: -55°C to +125°C
- Characteristic Impedance: 50Ω

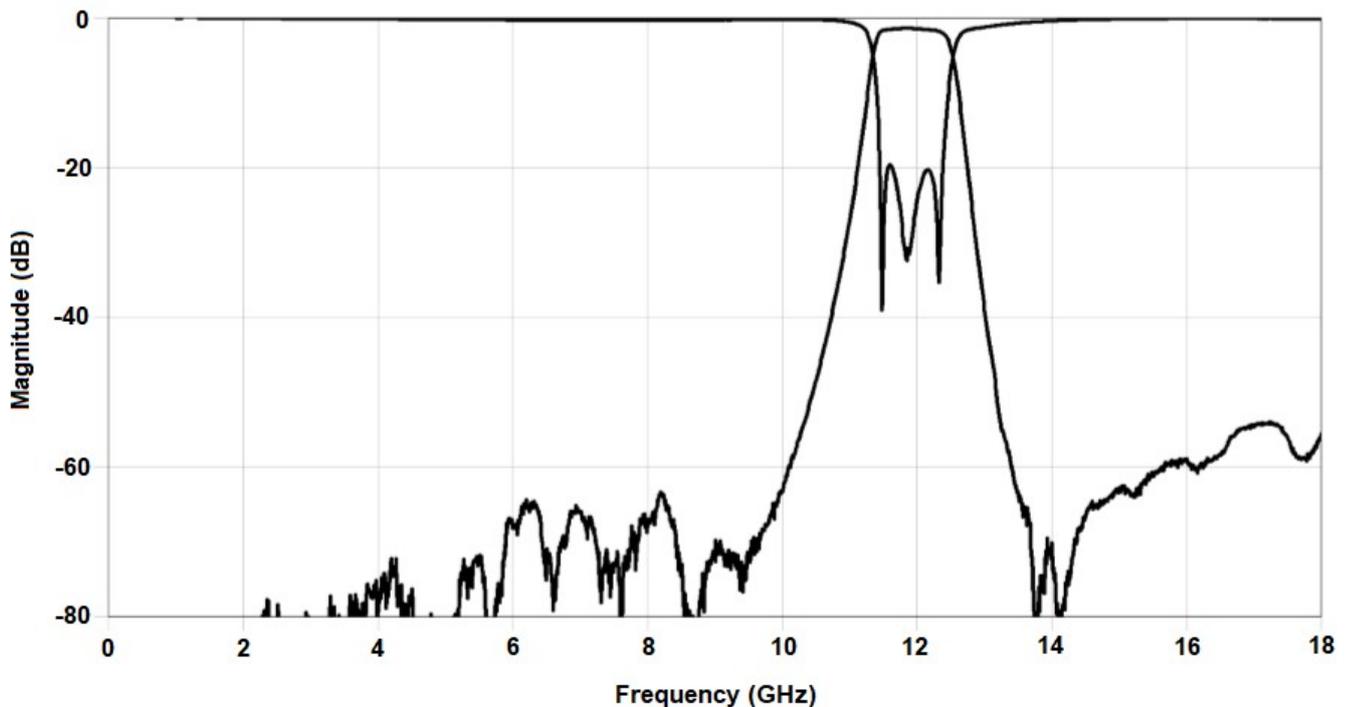
### Specifications\*

Parameter	Frequency Range (GHz)	Min	Typ.	Max
Insertion Loss (dB)	11.6 - 12.1		1.75	2.0
Return Loss (dB)		10	14	
Low Side Rejection (dB)	DC - 10.25	45	50	
High Side Rejection (dB)	12.5 - 13.25	45	50	
CW Input Power** (W)				10
$\theta_{jc} \left( \frac{^{\circ}\text{C}}{\text{W}} \right)$	7.5			
Size (L x W x H)	11.43 x 5.08 x 2.62 mm			

\*Electrical specifications based on typical probed performance at room temperature. Insertion loss shall vary  $\pm 0.5$ dB over temperature.

\*\*Power rating assumes the component will be mounted to a PCB with good thermally conducting ground vias as outlined in the recommended PCB layout that are connected to an adequate heat sink. Max power is based on 125°C base temperature.

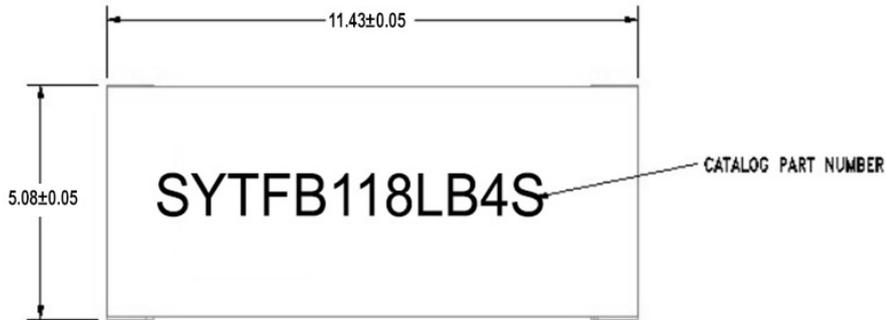
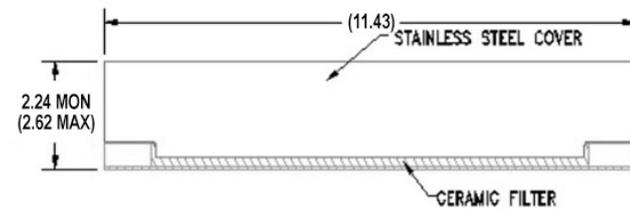
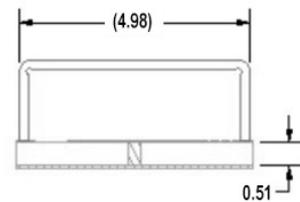
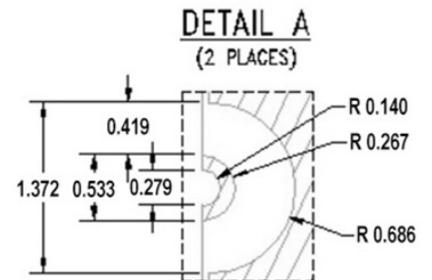
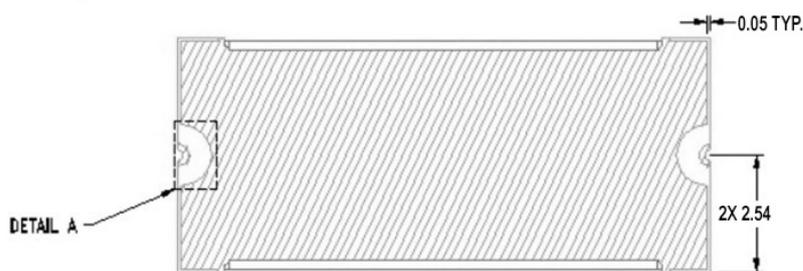
### Typical Measured Performance



\*Typical de-embedded measured performance mounted on a connectorized test fixture. DEB is 0.254mm RO4350B with 50.00ohm CPW ground traces going into the ports at room temperature.

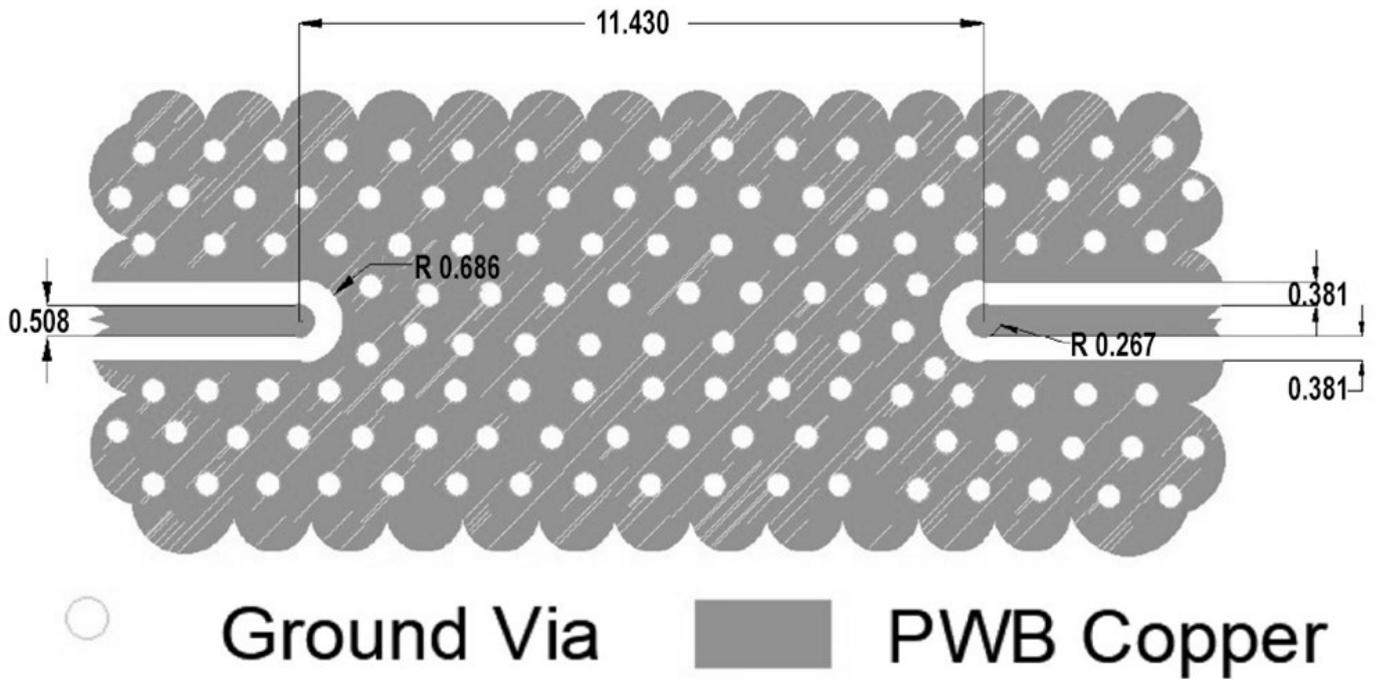
**Physical Dimensions**

Units = mm

**Top View**

**Side View**

**End View**

**Bottom View**

**Notes :**

1. Termination Finish:  
ENIG:  $76-152 \mu\text{m}$  Au over  $1270 \mu\text{m}$  Ni
2. Maximum Assembly Process Temperature:  $250^\circ\text{C}$
3. Dimension tolerance:  $\pm 0.05$

## Recommended PCB Layout



Unit =mm

### Note:

- 50Ω trace dimensions are application specific.
- Ensure adequate grounding beneath the part.